Supporting Information to:

## High-performance Top-gated Monolayer SnS<sub>2</sub> Field-effect Transistors and Their Integrated Logic Circuits

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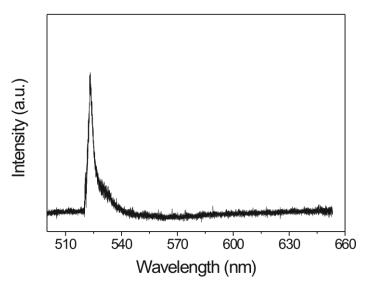


Figure S1. Micro-photoluminescence of single layer SnS<sub>2</sub> flake fabricated for TG-FET.

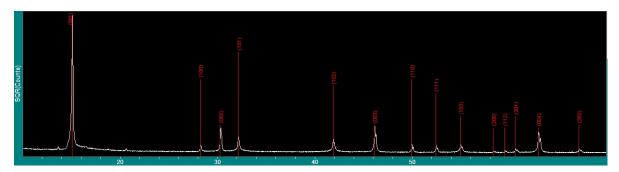


Figure S2. Powder XRD of  $SnS_2$  bulks, red lines denote from the standard card and the white peaks correspond to XRD data. The exfoliated source demonstrates pure hexagonal  $SnS_2$  with JCPDS NO.83-1706.

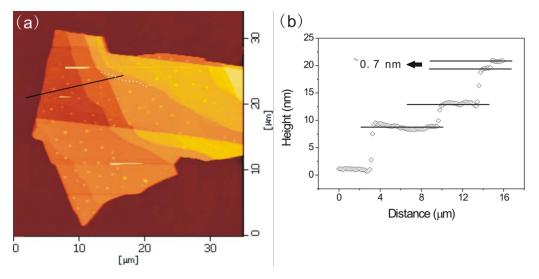


Fig.S3 (a,b) AFM image of multiple layer  $SnS_2$  flake and its height profile along the black line. The white dotted line shows the boundary of two neighbor layers and the height difference is ~0.7 nm. The 0.7 nm scanning demonstrate that our AFM instruments can identify monolayer scanning.

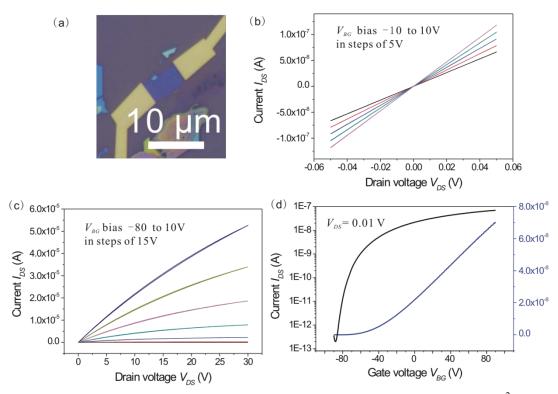


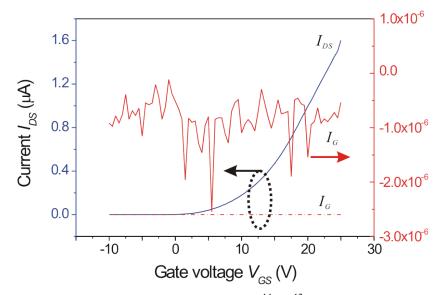
Figure S4. BG-FET performances with bare top surface, the carrier mobility is ~10 cm<sup>2</sup>/Vs. For the calculation to the BG-FET mobility: The BG-FET was measured in standard back-gated FET structure utilizing 285 nm SiO<sub>2</sub> covering layer with bare SnS<sub>2</sub> flake top surface as the channel. For the calculation of mobility, we utilize the linear working zone of FET as

$$\mu_{BG} = g_{m} \times \frac{L}{W} \times \frac{1}{C_{i}} \times \frac{1}{V_{DS}}$$
, while the transconductance  $g_{m} = \frac{dI_{DS}}{dV_{BG}}$  was extracted from Fig.

S2d,  $g_m=8\times10^{-10}$  A/V; the capacitance per unit area of SiO<sub>2</sub>,  $C_i=\varepsilon_0\varepsilon_r/d = 8.85\times10^{-12}$ F/m×3.9 /(285×10<sup>-9</sup> m)=1.21×10<sup>-8</sup> F/cm<sup>2</sup>; The ratio of channel length to width is ~5/3. Substituting all the

above data, we can get  $\mu_{BG} = g_{m} \times \frac{L}{W} \times \frac{1}{C_{i}} \times \frac{1}{V_{DS}} = 8 \times 10^{-10} \times \frac{5}{3} \times \frac{1}{1.21 \times 10^{-8}} \times 100 \text{ cm}^{2}/\text{Vs}$ 

 $\sim 10 \text{ cm}^2/\text{Vs}.$ 



**Figure S5**. Leakage current ( $I_G$ ) stands in the order of  $10^{-14}$ - $10^{-12}$  ampere during our measurement.